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Application Number	10/612,112
Filing Date	08/02/2003
First Named Inventor	Jacob Fraden
Art Unit	2859
Examiner Name	Verbitsky, Gail Kaplan

ENCLOSURES (Check all that apply)

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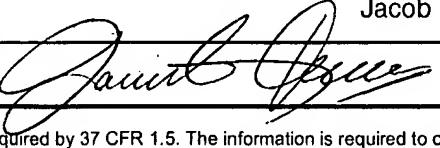
*In response to communication
of 09/14/2004*

SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT

Firm or Individual name	Jacob Fraden, Advanced Monitors Corporation	
Signature		
Date	9/14/04	

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In The Claims:

This listing of claims will replace all prior versions and listings of respective claims in the application:

1. (Currently Amended) A probe of a medical instrument that is intended for insertion into a patient's body orifice, such probe has an inner surface and the outer surface which is shaped to contain at least one cavity encircled by a ridge.
2. (Currently Amended) A probe of claim 1 where said cavity is covered by outer thin skin that is permanently attached to said outer surface ridge.
3. (Cancelled)
4. (Currently Amended) A probe of claim 3 1 where said which contains multiple cavities being are randomly distributed along said outer surface.
5. (Original) A probe of claim 1 is fabricated of material having low thermal conductivity
6. (Original) A probe of claim 1 further comprises a polymer probe cover that envelopes said outer surface.
7. (Original) A method of thermal insulation of a medical probe, comprising a step of forming indentations on the outer surface of the probe.
8. (Currently Amended) A method of thermal insulation of a medical probe of claim 7, further comprising a step of covering said indentations with a layer of thin protective material having low thermal conductivity.